

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	228	wafer and (vacuum with chamber) and ((humidity or moisture) with (sensor or detector or control or controller)) and (cleaning or cleaner)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 02:24
L2	15	wafer and (vacuum with chamber) and ((humidity or moisture) with (sensor or detector or control or controller)) and (cleaning or cleaner) and "156"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:02
L3	3	((("5421953") or ("5934856") or ("20030168145")).PN.	US-PGPUB; USPAT	OR	OFF	2006/01/23 02:16
L4	17	US-5371037-\$.DID. OR US-5763288-\$.DID. OR US-5374564-\$.DID. OR US-5994207-\$.DID. OR US-6156624-\$.DID. OR US-6171932-\$.DID. OR US-6383890-\$.DID. OR US-6451670-\$.DID. OR US-6150031-\$.DID.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 02:13
L5	9	US-5371037-\$.DID. OR US-5763288-\$.DID. OR US-5374564-\$.DID. OR US-5994207-\$.DID. OR US-6156624-\$.DID. OR US-6171932-\$.DID. OR US-6383890-\$.DID. OR US-6451670-\$.DID. OR US-6150031-\$.DID.	USPAT	OR	ON	2006/01/23 02:13
L6	5	((("20020004286") or ("20020174958") or ("20020174959") or ("20030003687") or ("20030010445")).PN.	US-PGPUB; USPAT	OR	OFF	2006/01/23 02:16
L7	523	(156/359).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/23 02:24
L8	467	(156/351).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/23 02:59
L9	3	"156"/\$.ccls. and ((humidity or moisture) with (sensor or detector or control or controller)) and (wafer with (bonding or bonder))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 02:25

L10	277	(156/360).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/23 02:59
L12	799	(156/378).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/23 02:59
L13	232	(156/379).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/23 02:59
L14	0	(wafer with SOI with bonding) and (vacuum with chamber) and ((humidity or moisture) with (sensor or detector or control or controller)) and (cleaning or cleaner)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:02
L15	0	(wafer with SOI with bonding) and ((humidity or moisture) with (sensor or detector or control or controller)) and (cleaning or cleaner)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:02
L16	9	(wafer with SOI with bonding) and ((humidity or moisture) with (sensor or detector or control or controller))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:14
L17	96	(wafer with SOI with bonding) and ((pressure) with (sensor or detector or control or controller))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:09
L18	8	(wafer with SOI with bonding) and ((pressure with chamber) with (sensor or detector or control or controller))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:10

L19	10	(wafer with SOI with bonding) and ((pressure with chamber) same (pressure with (sensor or detector or control or controller)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:13
L20	358	(wafer with bonding) and ((pressure with chamber) same (pressure with (sensor or detector or control or controller)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:13
L21	11	(wafer same (SOI with bonding)) and ((pressure with chamber) same (pressure with (sensor or detector or control or controller)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:13
L22	725	(wafer with SOI with bonding) and (activation iwth state)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:15
L23	7	(wafer with SOI with bonding) and (activation with state)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:16
L24	8	(wafer with SOI with bonding) and (activation same plasma)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:35
L25	15	(wafer with SOI with bonding) and (environmental with (sensor or detector or control or controller))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:37
L26	246	(wafer with bonding) and (environmental with (sensor or detector or control or controller))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:41

L27	1	(wafer with bonding) and (environmental with (sensor or detector or control or controller)) and "156"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:41
L28	1	(wafer with bonding) and (environmental with (sensor or detector or control or controller)) and "156"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:41
L29	1	(wafer with bonding) and (environmental with (sensor or detector or control or controller)) and "156"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:43
L30	3	(chamber with bonding) and (environmental with (sensor or detector or control or controller)) and "156"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:44
L31	5	(chamber with bonding) and (humidity with (sensor or detector or control or controller)) and "156"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:44
L32	11	(chamber with bonding) and (moisture with (sensor or detector or control or controller)) and "156"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:45
L33	14	(wafer with processing with chamber) and (moisture with (sensor or detector or control or controller)) and "156"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:47
L34	129	(wafer with processing with chamber) and (moisture with (sensor or detector or control or controller))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 03:46